Neutron Irradiations and Punch-Through-Biasing Studies with DEPFETs for BELLE II

13th International Workshop on DEPFET Detectors and Applications

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Outline

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   2. Punch-through biasing
   3. Punch-through noise

II. **DUTs and pre-characterizations**
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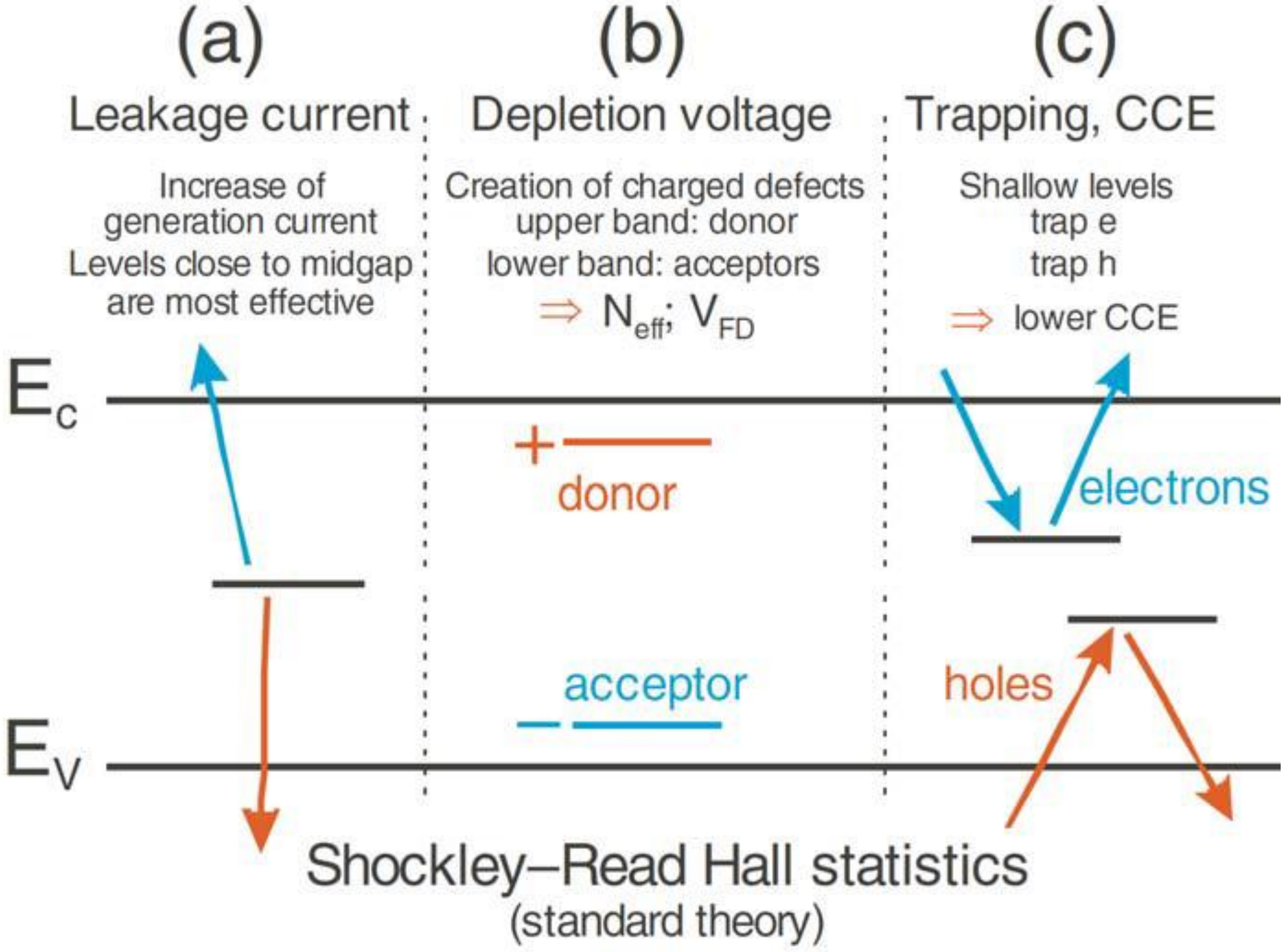
   2. Pre-characterization of devices

III. **Results**
   1. Increase of leakage current
   2. Change in full depletion voltage
   3. DEPFET performance
   4. Punch-through noise

Theoretical Background

Bulk Damage – Defect energy levels

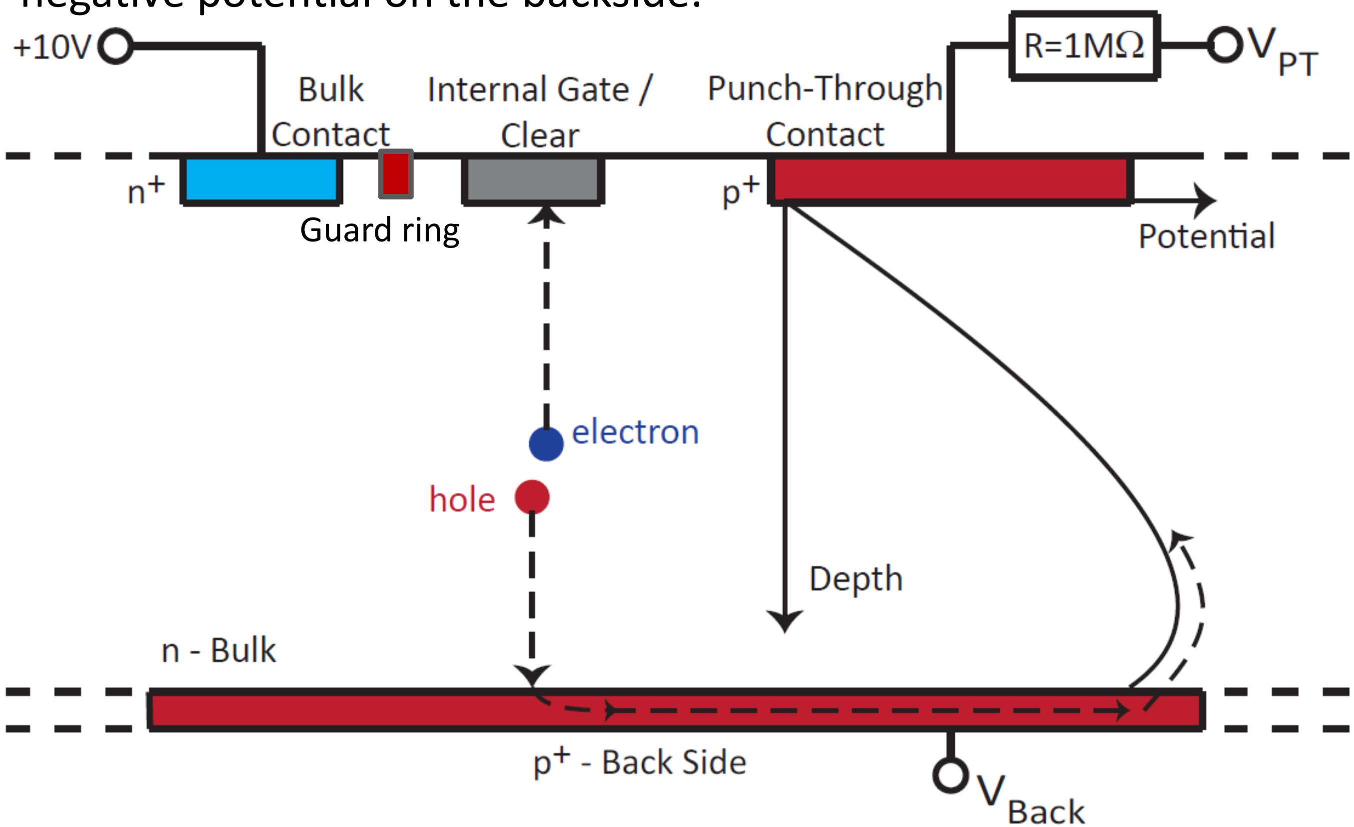


Evolution of Silicon Sensor Technology in Particle Physics.
Frank Hartmann. Springer, 2008.

Punch-Through Biasing

Aim: Design of a biasing structure, which does not require additional backside processing and which facilitates back side contacting of the device

→ Applying a negative voltage at the punch-through contact on the top side will result in a smaller negative potential on the backside.



The punch-through current will be formed by holes traversing from the back to the punch-through contact, while overcoming a potential barrier in the bulk

Punch-Through Biasing

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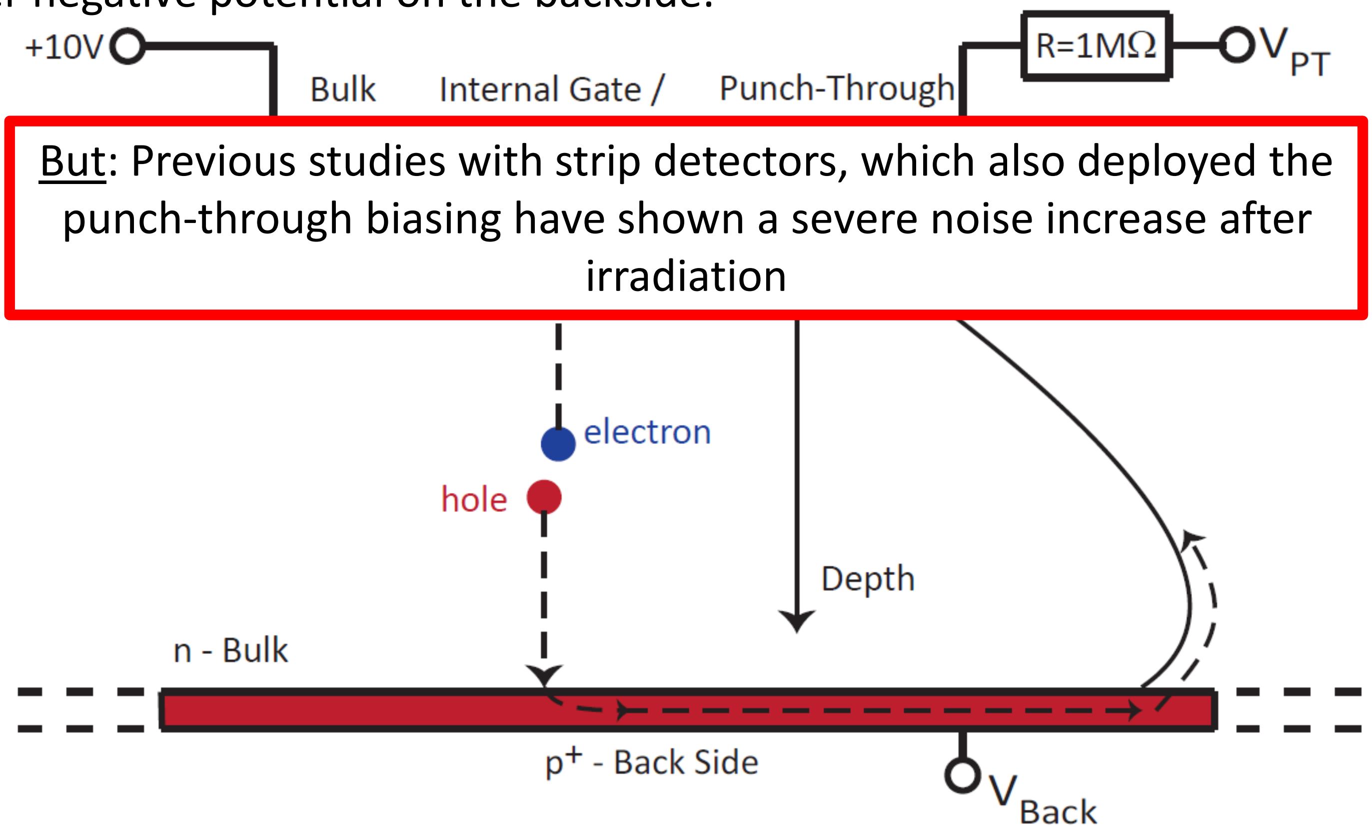
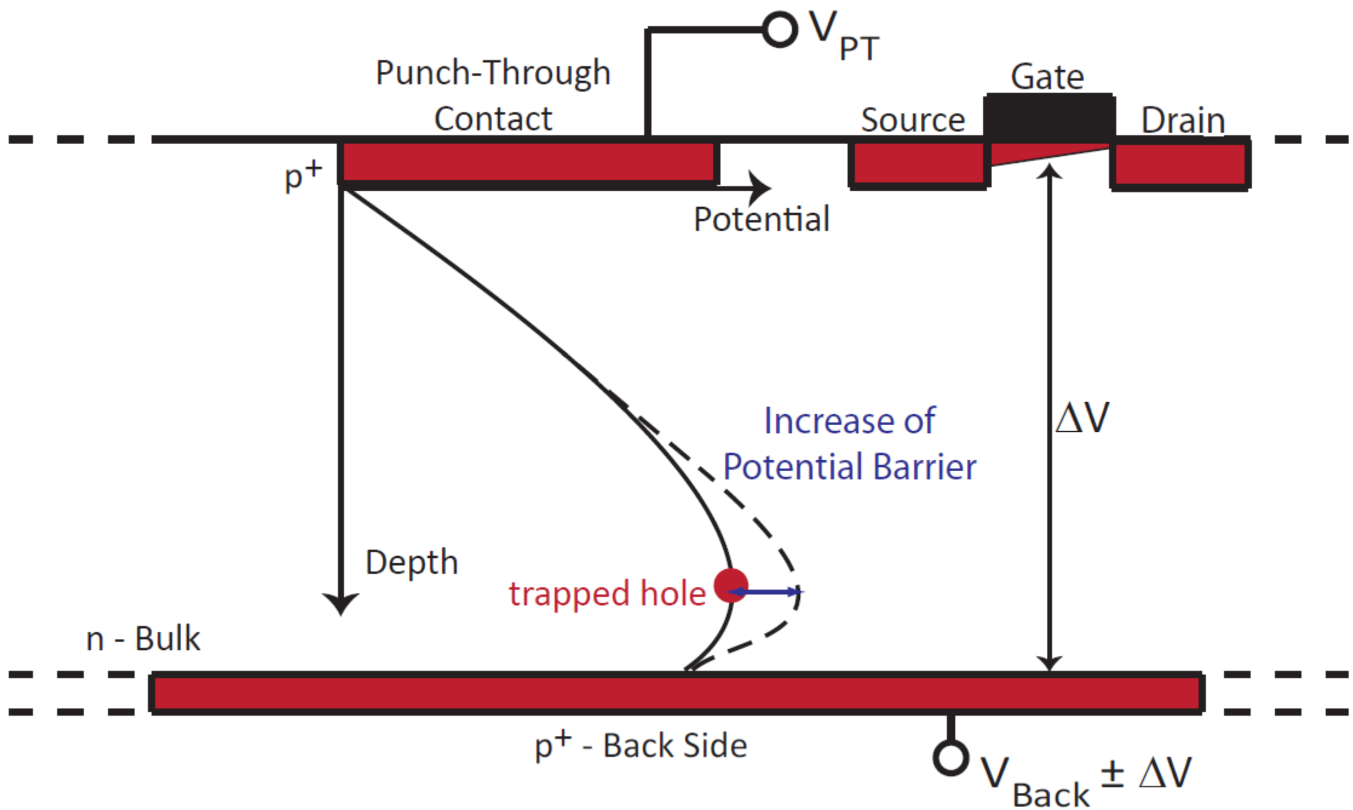


But: Previous studies with strip detectors, which also deployed the punch-through biasing have shown a severe noise increase after irradiation

The punch-through current will be formed by holes traversing from the back to the punch-through contact, while overcoming a potential barrier in the bulk

Possible Punch-Through Noise

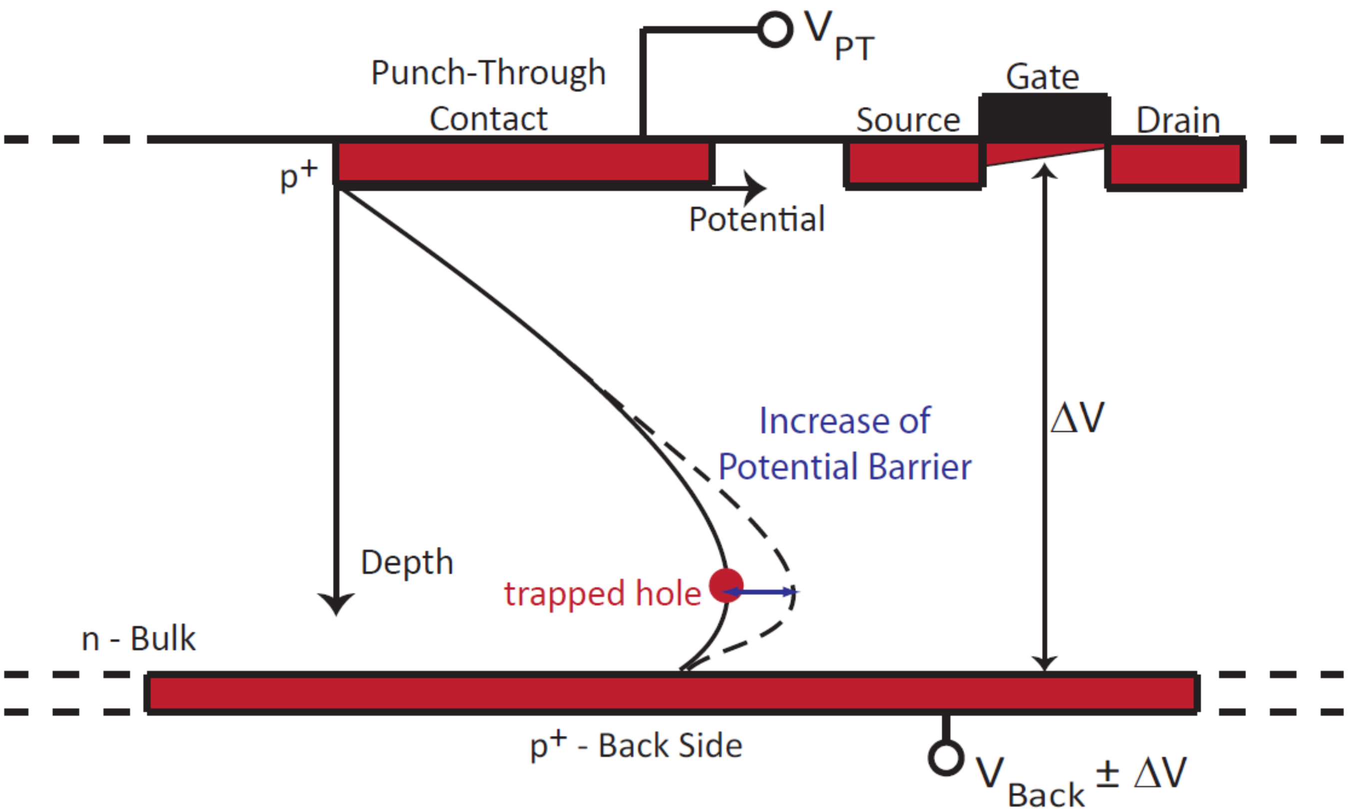


Bulk defects can trap holes and thereby affect the potential on the backside of the detector:

▪ while charges are trapped the potential barrier becomes more difficult to overcome and thus more holes remain on the backside → + ΔV

▪ releasing the trapped charges results in an abrupt “slop over“ of holes which leads to a drastic decrease in hole-concentration on the backside → - ΔV

Possible Punch-Through Noise



➔ variations ±ΔV of the backside-potential could be able to affect the signal of the MOSFET structure by means of capacitive couplings to the MOSFET channel

➔ should be a 1/f – like noise contribution

➔ influence expected to be rather small

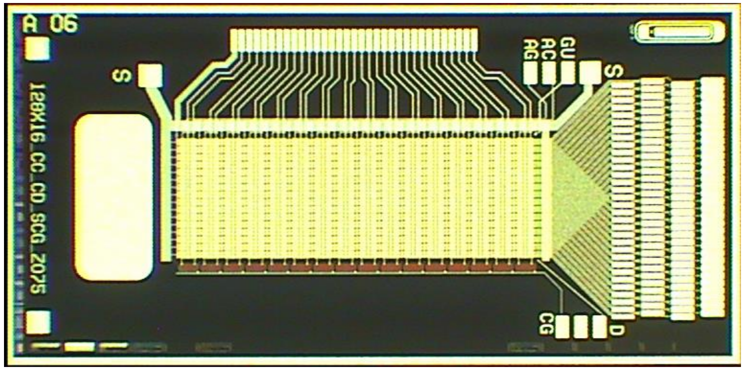
Goals

- measurement of the punch-through biasing characteristics
- characterization of punch-through noise
- investigation of the behavior of punch-through biasing characteristics and punch-through noise after neutron irradiation
- measurement of type inversion and leakage current increase after neutron irradiation on both diodes and DEPFET matrices
- evaluation of the change in behavior of the DEPFET matrices after certain radiation doses due to radiation induced damages in the bulk

→ analysis if these effects have a significant impact on the DEPFET performance

DUTs and pre-characterizations

DEPFET matrices and diodes

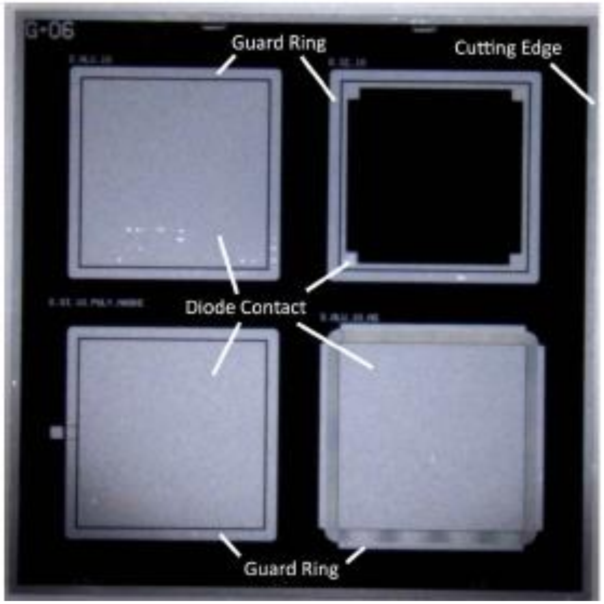


DEPFET PXD6 Matrices:

- 50µm x 75µm pixel size, 50µm thickness, capacitive coupled cleargate
- 400 Ωcm resistivity
- punch-through and direct back side biasing
- measurements were performed with the MiniMatrix (MiMa) setup
- 48 available DEPFET pixels (8 drains and 6 gates)

Silicon diode chips:

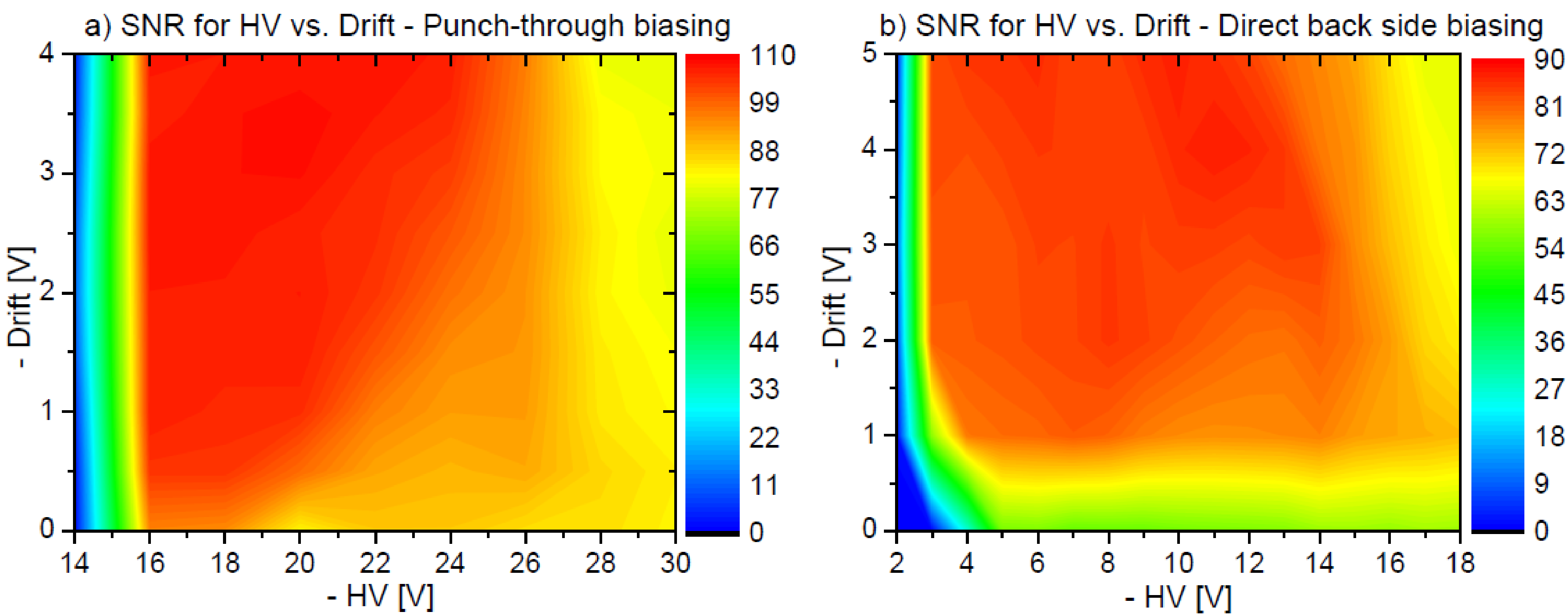
- two sets of diode chips with 100 Ωcm and 400 Ωcm resistivity
- each chip contains 4 diodes with A = 0.1 cm^2 and 75µm/ 50µm thickness (100 Ωcm/400 Ωcm)
- guard ring
- back side biasing via the cutting edge



Pre-characterizations: Matrices and diodes

- pre-characterization of diodes in terms of depletion voltage and leakage current with the PA150 probe station
- DEPFET matrix characterizations in both biasing methods included:
  - laser measurements for different voltage parameters (HV, Drift, ClearLow, ClearHigh, ClearGate) in order to determine the optimal operation point of each matrix
  - measurements of the Fe^{55} spectrum, allowing the determination of the internal amplification
  - dark measurements in order to evaluate the leakage current and noise of each pixel

→ no negative impact of the punch-through biasing method



Neutron irradiations

• all devices were irradiated at
the JSI TRIGA reactor in Ljubljana, Slovenia

• two sets of diodes were irradiated
with neutron fluences (according to NIEL scaling)
ranging from 10^{11}, $5\text{x}10^{11}$, 10^{12}, … to $5\text{x}10^{14}$ neq/cm^2

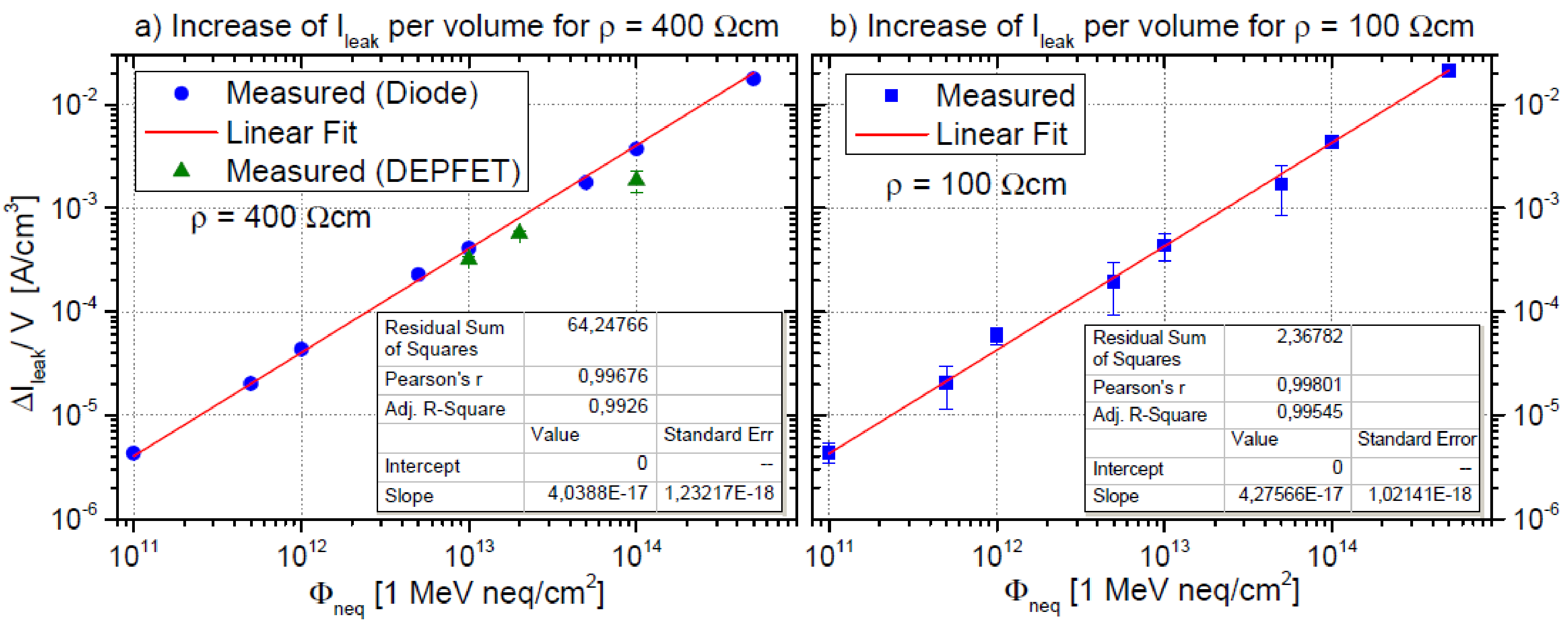
• DEPFET matrices were irradiated with
neutron fluences of $1\text{x}10^{13}$, $2\text{x}10^{13}$ and $1\text{x}10^{14}$ neq/cm^2

• expected final BELLE II fluence after
ten years of operation (calculated with NIEL scaling):
$\phi_{neq} = 2\text{x}10^{13}$ neq/cm^2

→ the chosen neutron fluences should cover the entire BELLE II operation time span

Results

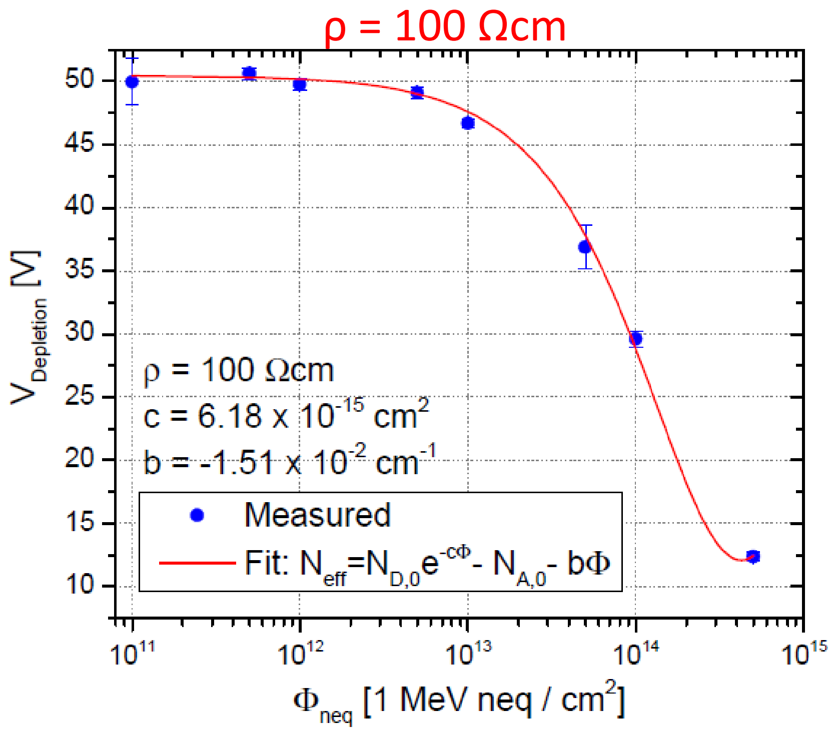
Increase of leakage current

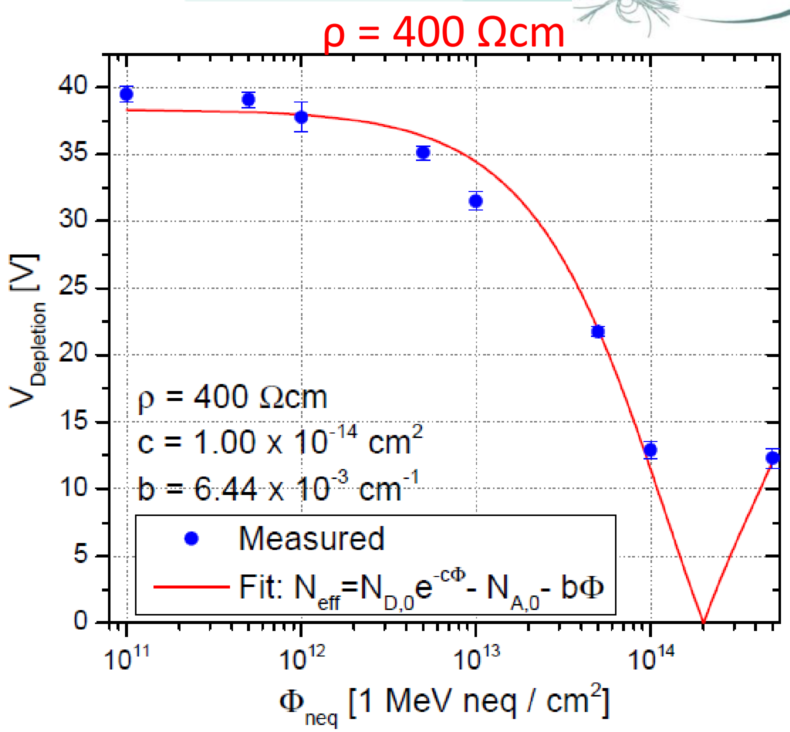


- measurement of leakage currents per volume of diodes and DEPFET matrices after neutron irradiation
- all values normalized to the reference temperature of 20°C

→ material independent increase of leakage currents
→ in excellent agreement with previous studies
→ no unexpected behavior for DEPFETs

Change in full depletion voltage



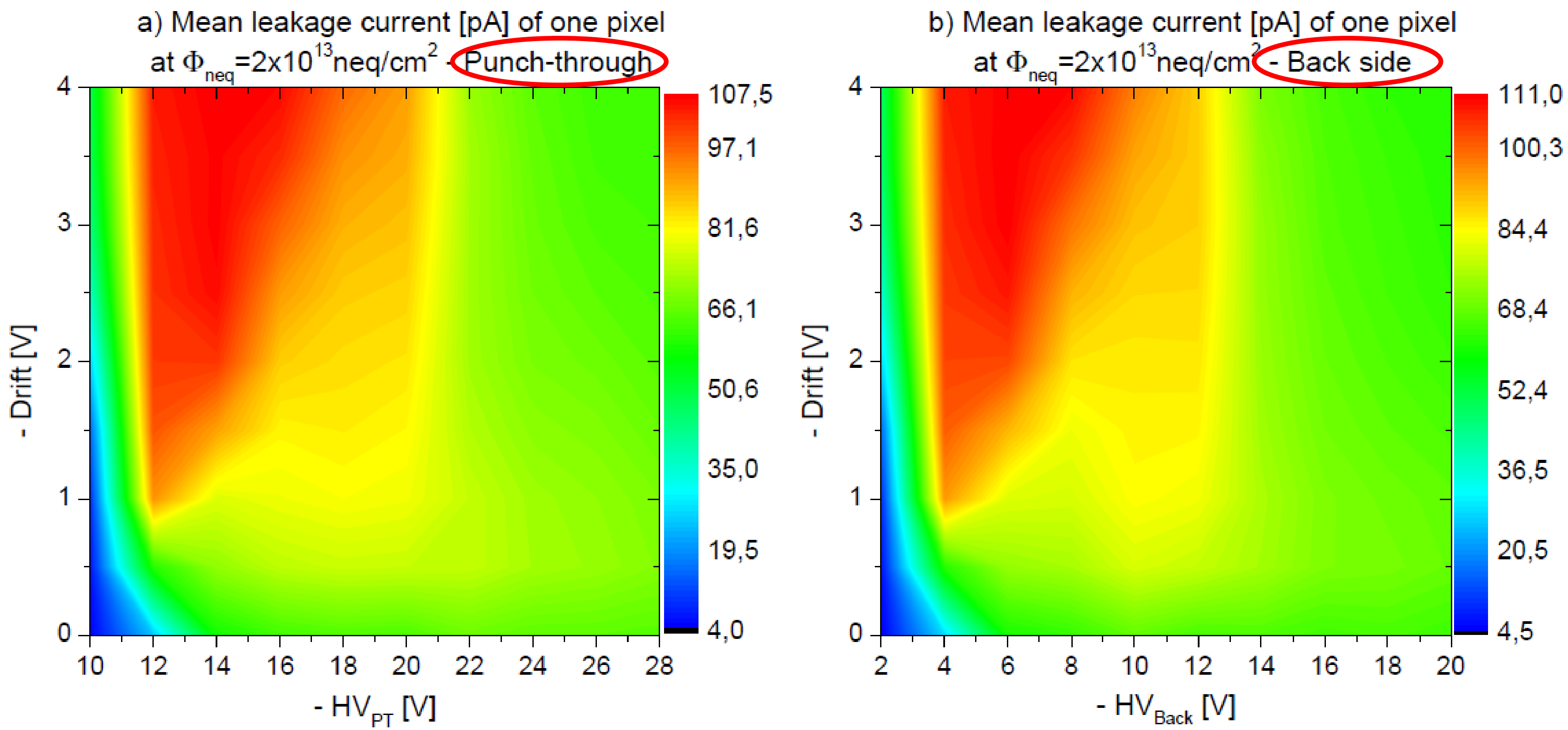


<u>Measurement of full depletion voltage of diodes after different neutron fluences:</u>

- initial decrease of depletion voltage in both cases
- type inversion of 400 Ωcm material at approximately 2×10^{14} neq/cm^2
- increase of depletion voltage after type inversion
- no type inversion in the case of 100 Ωcm material

→ lower resistivity material is more radiation hard in terms of type inversion
→ no type inversion of DEPFET structures after ten years of BELLE II operations ($\phi = 2 \times 10^{13}$ neq/cm^2)

Performance of DEPFET matrices



Measurements of DEPFET matrix behavior after certain neutron fluences showed:

- DEPFET matrices were still functional up to a neutron fluence of $\phi = 1x10^{14}$ neq/cm^2
- shift of optimal voltage parameters due to decreasing full depletion voltage and threshold voltage shifts of the gate structures

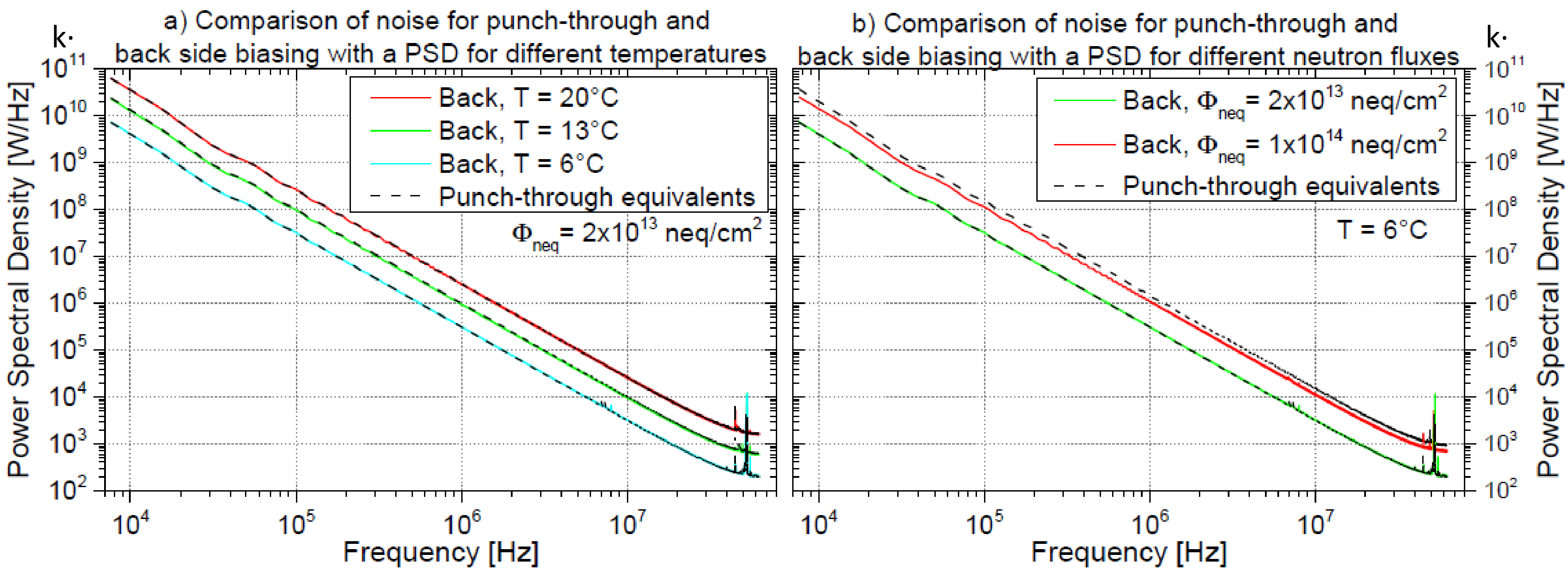
Performance of DEPFET matrices

- no type inversion up to $\phi = 1\text{x}10^{14}$ neq/cm^2
- decrease in charge handling capacity of the internal gate due to the threshold voltage shift of the clear gate
- increased leakage currents should pose no threat (@ 20°C) for the charge handling capacity of the internal gate, if adjustments to the clear gate and clear low voltages are made

Neutron fluence	$1 \cdot 10^{13}$ neq/cm^2	$2 \cdot 10^{13}$ neq/cm^2	$1 \cdot 10^{14}$ neq/cm^2
I_{leak}/V [A/cm^3]	$(3.2 \pm 0.2) \cdot 10^{-4}$	$(5.7 \pm 0.3) \cdot 10^{-4}$	$(1.85 \pm 0.44) \cdot 10^{-3}$
I_{leak}/Pixel [pA]	61.1 ± 4.2	107 ± 5.3	347 ± 81.6
$e^-/20\mu s$ [# e^-]	7361 ± 506	12891 ± 638 → shot noise: ≈113 e^-	41807 ± 9831
fill level of the internal gate [%]	10.5 ± 0.7	18.4 ± 0.9	59.7 ± 14

→ additional measurements with type inverted DEPFETs desirable

Punch-through noise

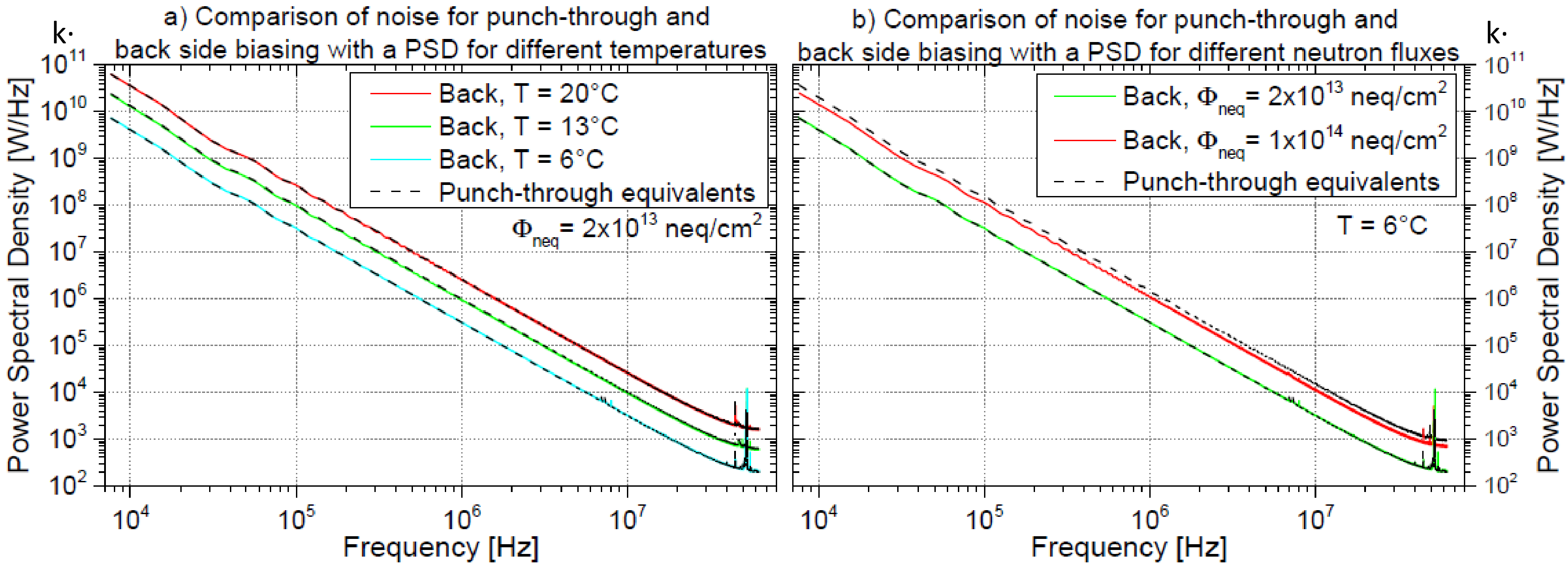


<u>Four different methods for determination of the punch-through noise were applied:</u>

- correlated double sampling
- linear fitting of the increasing pixel signal
- detailed evaluation of the time evolution of the pixel noise
- Fast Fourier Transformation of the measured signal and determination of the resulting power spectral density

All methods were applied in both biasing modes in order to determine noise differences

Punch-through noise



→ no additional 1/f noise component due to punch-through biasing could be detected in the measurements of all different measurement methods
→ no detectable impact of the punch-through noise up to a neutron fluence of $\phi = 1\text{x}10^{14}$ neq/cm^2

Summary

• no negative impact on the general and noise performance due to punch-through biasing before irradiations

• increased radiation hardness of lower resistivity material in terms of type inversion

• radiation hardness of DEPFET sensors for ten years of BELLE II operations (and even longer) in terms of type inversion

• operability of DEPFETs at 20°C in terms leakage currents and charge handling capacity of internal gates

• radiation hardness of the punch-through biasing method

• no detectable punch-through noise up to a fluence of $\phi = 1x10^{14}$ neq/cm^2

→ overall radiation hardness of DEPFET sensors for deployment at BELLE II confirmed
→ the punch-through biasing method is a suitable means of biasing the DEPFET without negative effects of the noise performance

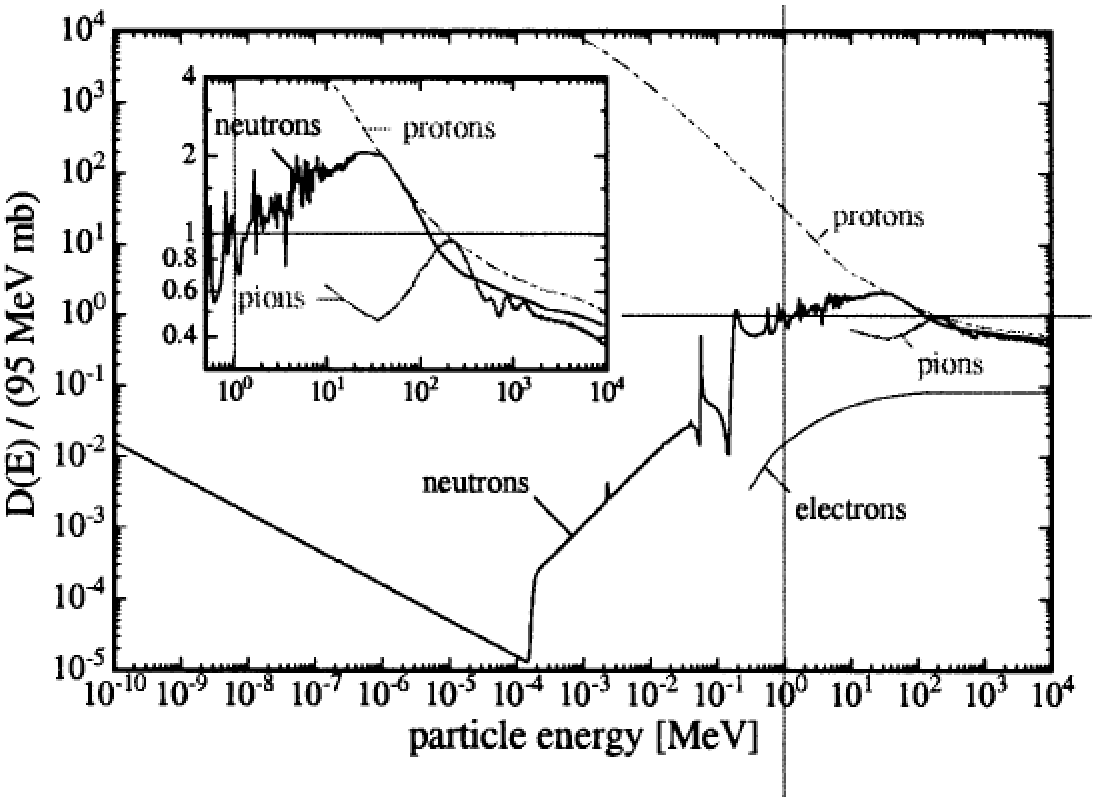
The End

Thank You For Your Attention!

Backup

Bulk Damage – NIEL Hypothesis

- incident particle hits atom in the lattice and creates a PKA (Primary Knock on Atom)
- incident particle and PKA are able to traverse through the bulk and loose energy via ionization and the creation of additional crystal displacements -> Cluster
- PKA and vacancies can also interact with impurity atoms to form point defects
- different types of particles have different impacts on the bulk

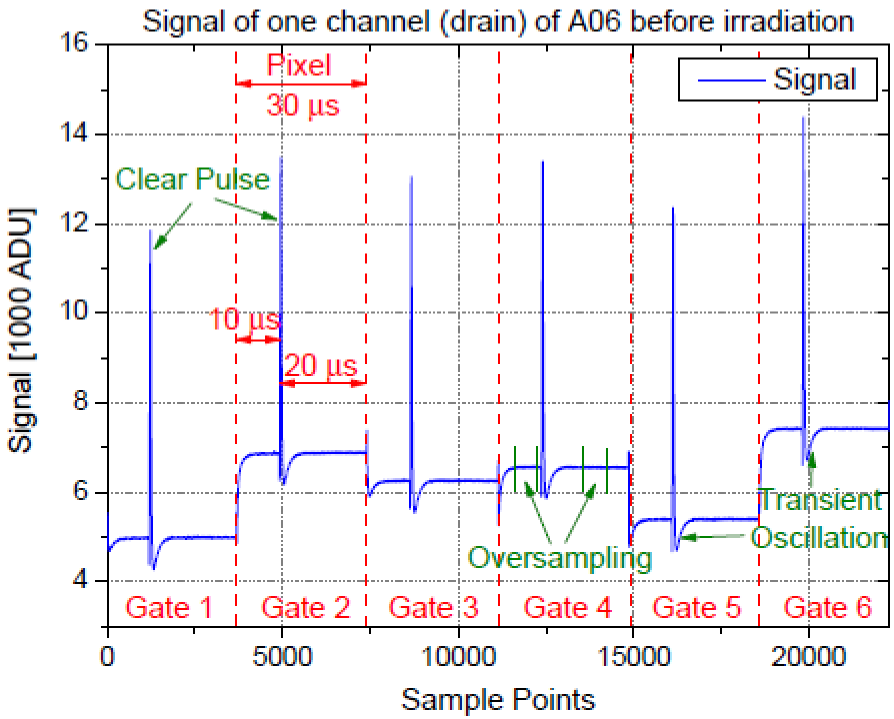


→ **NIEL-scaling hypothesis**

Particles have different hardness factors in order to compare them to neutrons

→ Allows calculation of the equivalent of 1 MeV neutron-induced damage

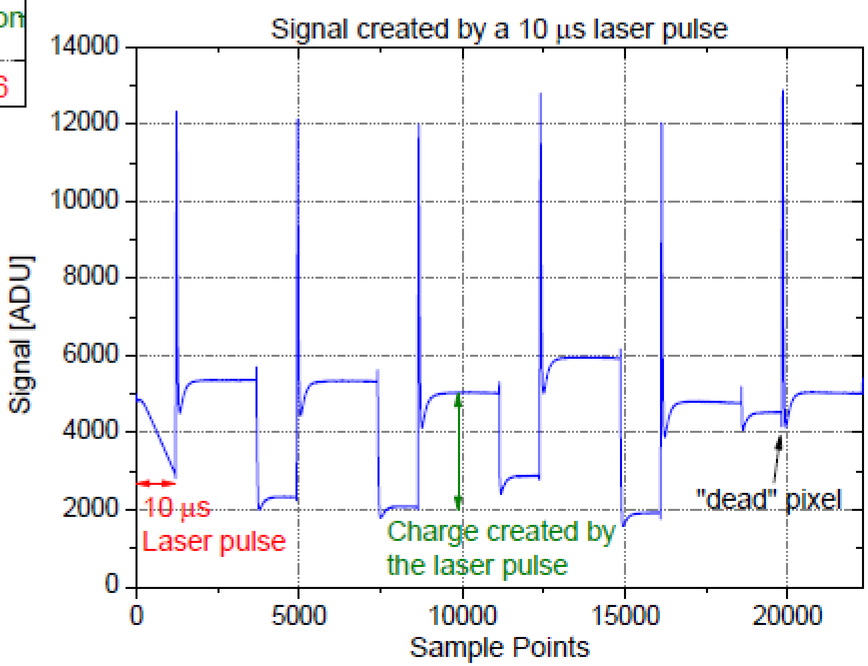
Experimental Setup: MiMa



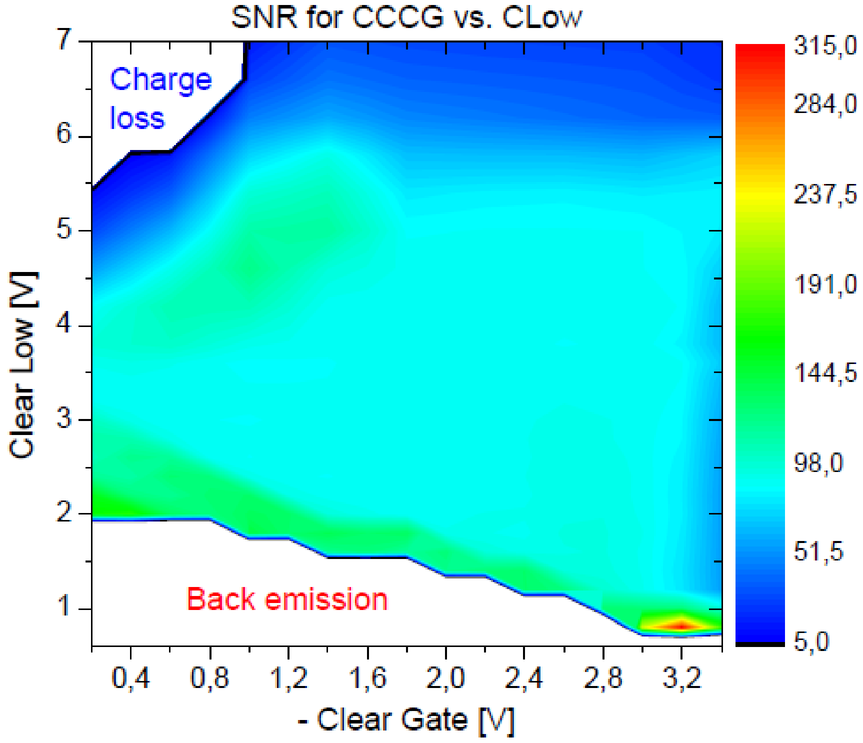
1 SP ≙ 8ns

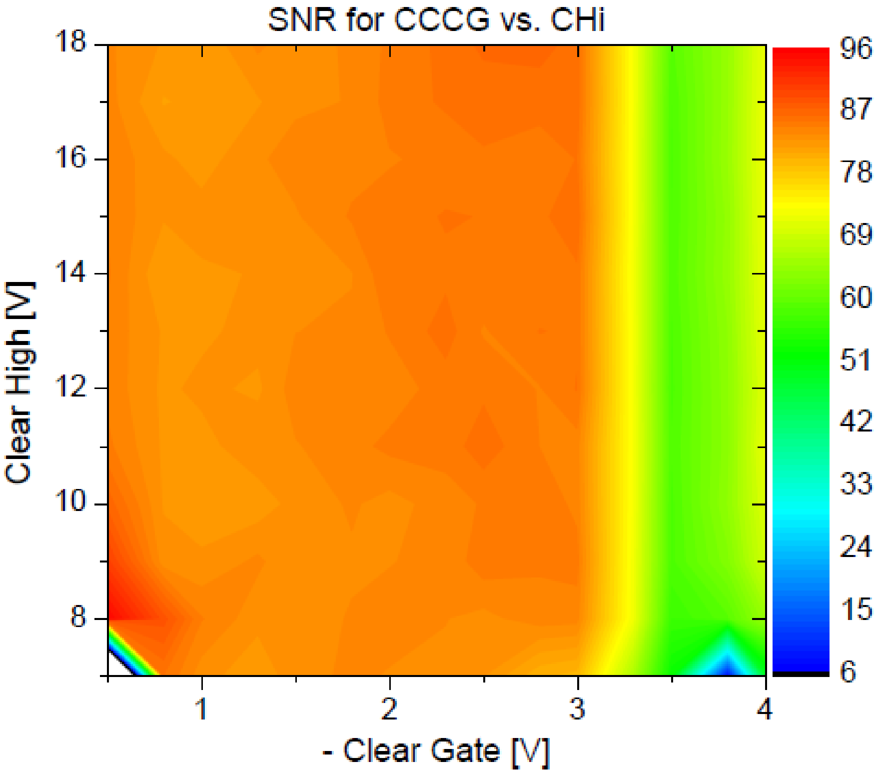
"Dark measurement"

Measurement with a laser pulse



Pre-characterizations: Matrices and diodes





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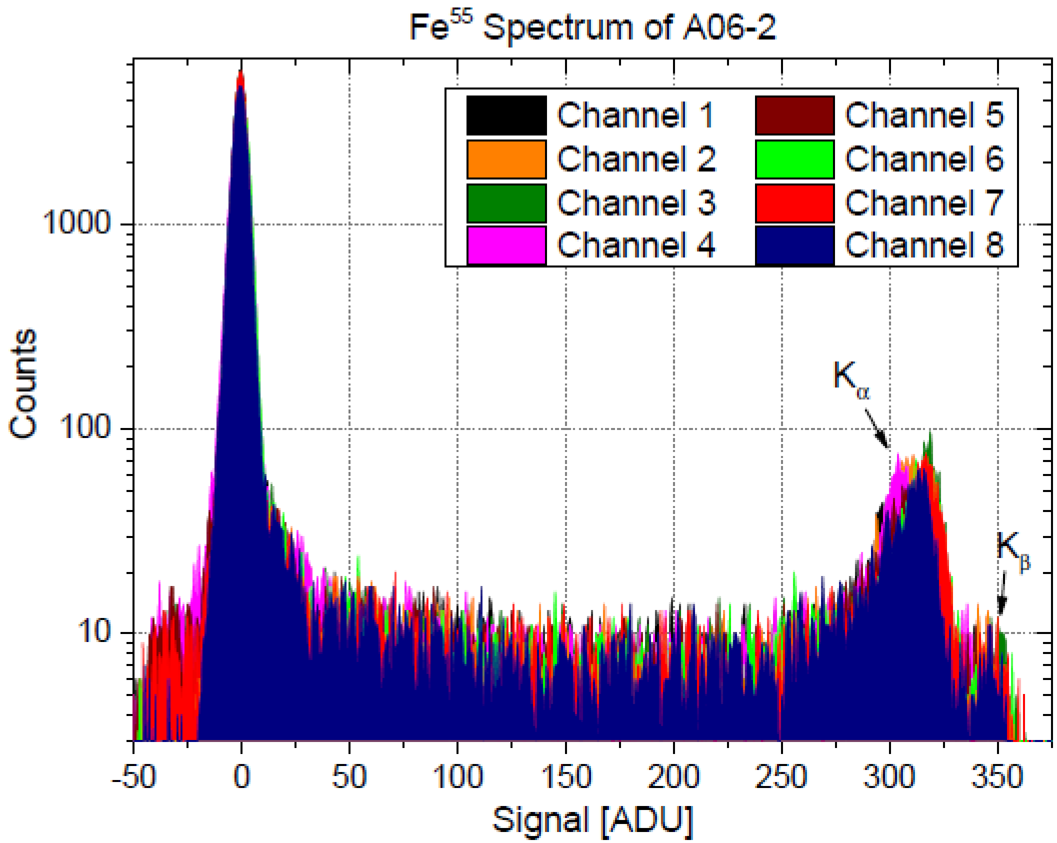
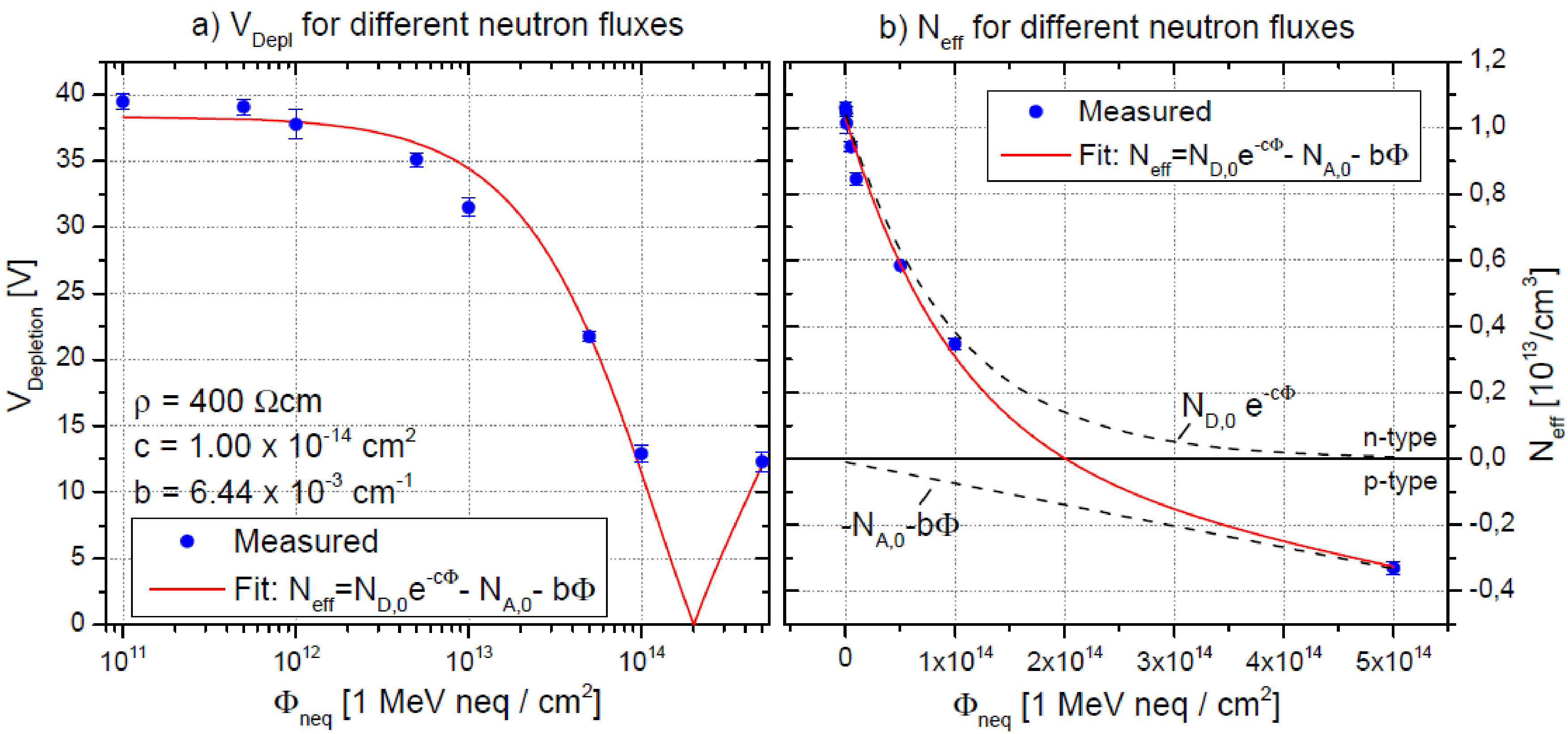


Calibration of the internal amplification of the DEPFETs with a Fe^{55} source

$\sigma \approx 30\ e^-$

	A06	K01	A06-2
g_q [pA/e^-]	391.3 / 454.1	401.6	391.2
ADU-to-electron	1 ADU $\hat{=}$ 5.26 / 4.53 e^-	1 ADU $\hat{=}$ 5.12 e^-	1 ADU $\hat{=}$ 5.26 e^-

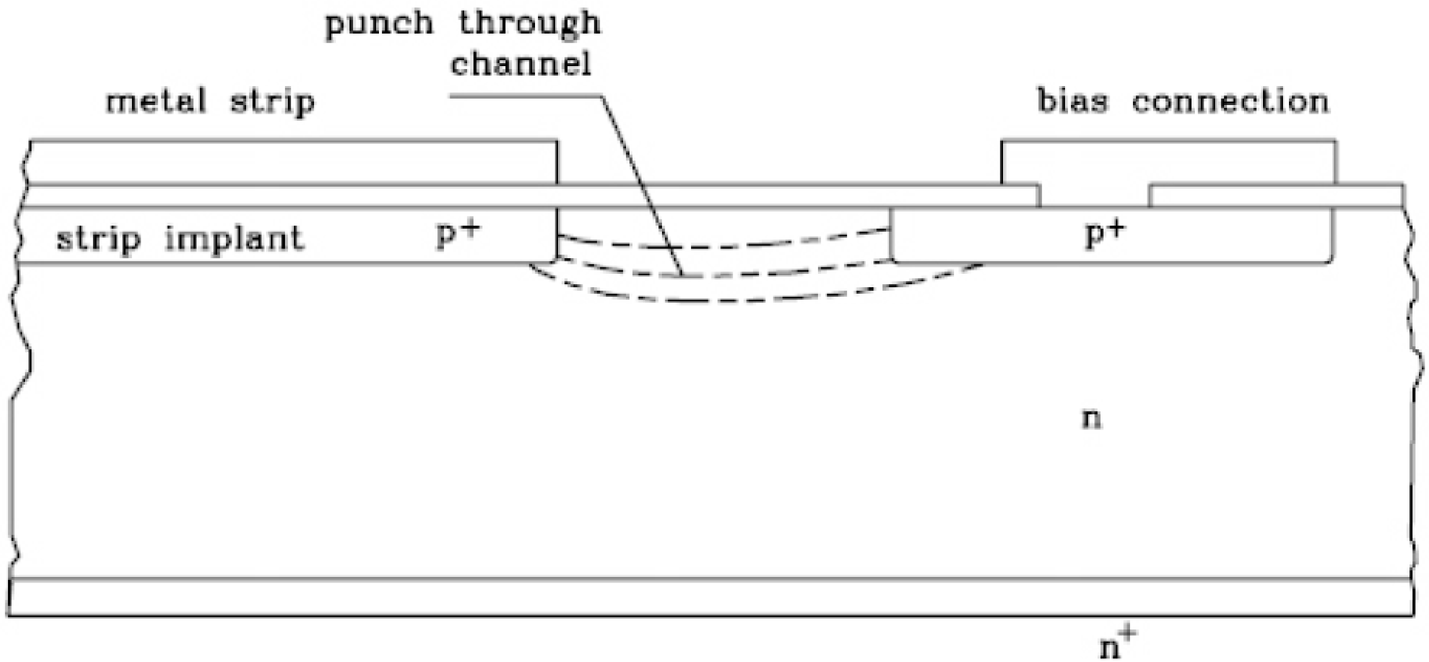
Type inversion – Fit parameter



- applying a fit function on the measured data in order to obtain the fit parameters c and b
- fit parameters were extracted for both resistivities and compared to previous studies

→ comparisons were possible but additional investigations are required

Punch-Through - FOXFET



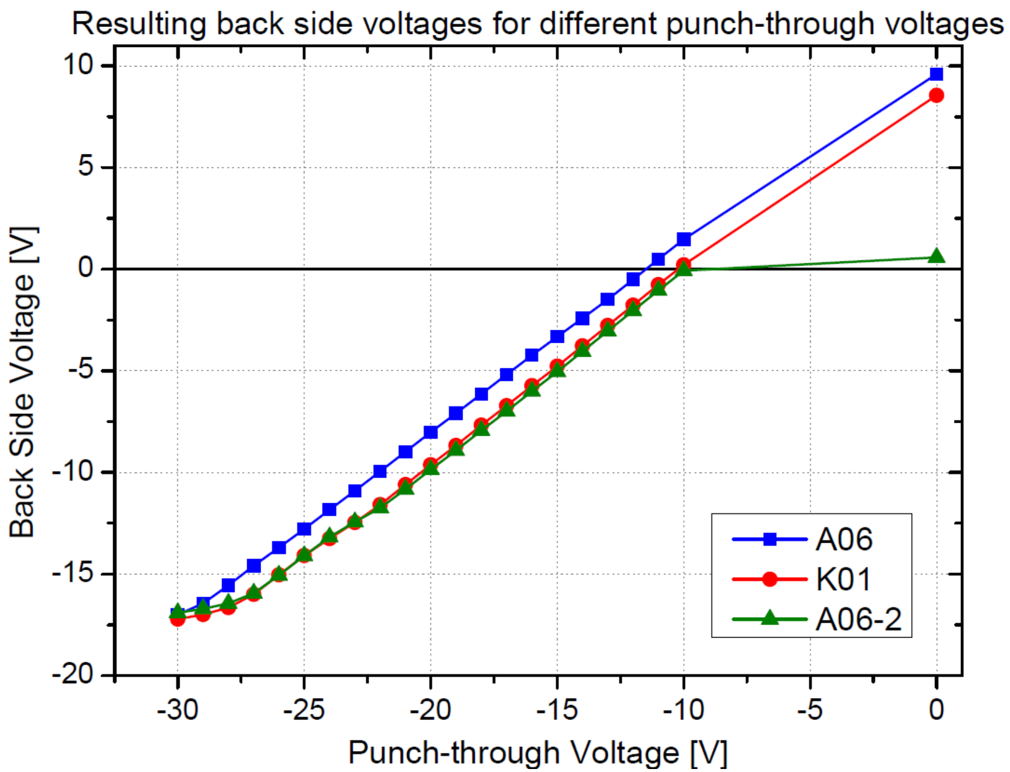
every strip has its own punch-through biasing structure

→ smaller area

→ direct feedback of trapping states in surface channel to the signal readout

→ increased noise

Pre-characterizations: Punch-through biasing



→ change in back side potential even before the punch-through current is established
→ result of capacitive couplings to the back side electrode

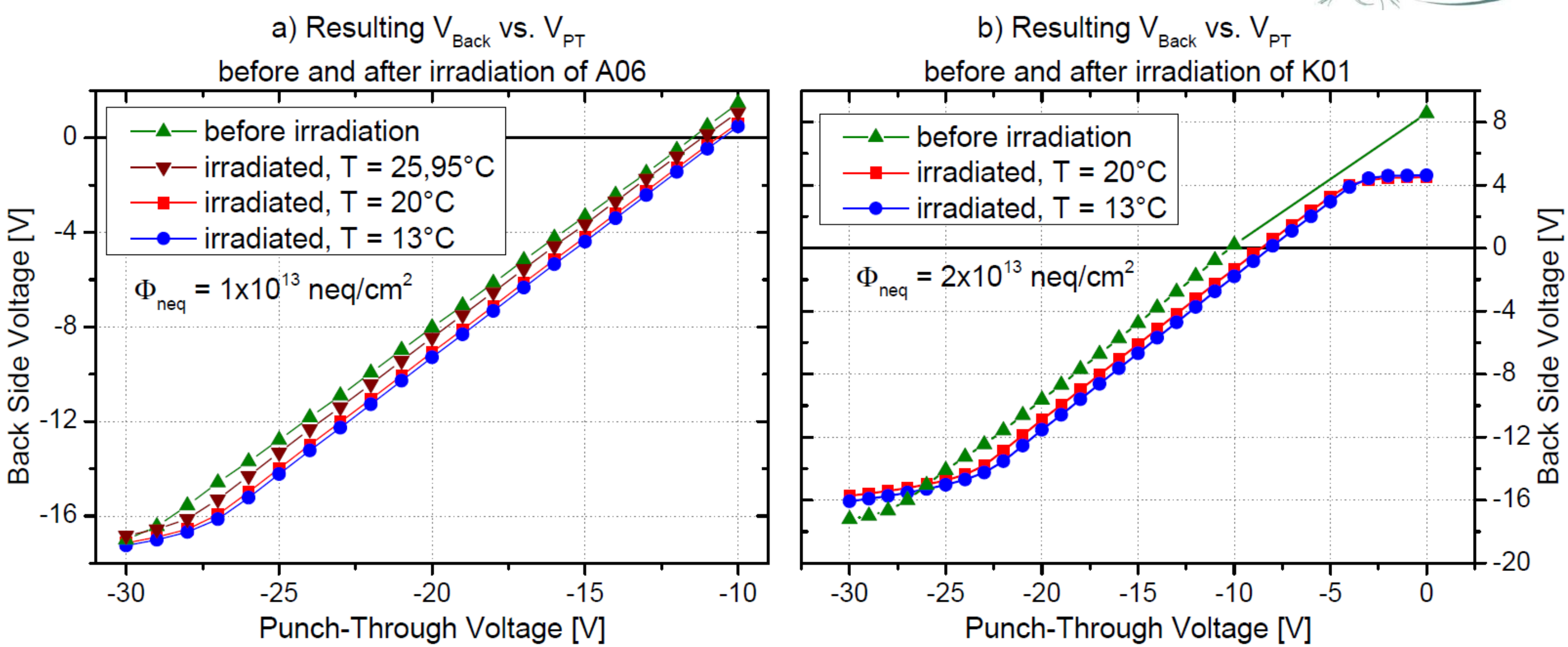
<u>Measurements of the punch-through biasing characteristics with an external source meter:</u>

• resulting back side voltage for different applied punch-through voltages
→linear correlation

• back side voltage – bulk current characteristics
→exponential behavior

• resulting back side voltage in dependence of the bulk current
→ only very small changes for increasing bulk current

Punch-through biasing



- repetition of the punch-through biasing measurements showed a smaller voltage drop in the detector bulk after irradiation

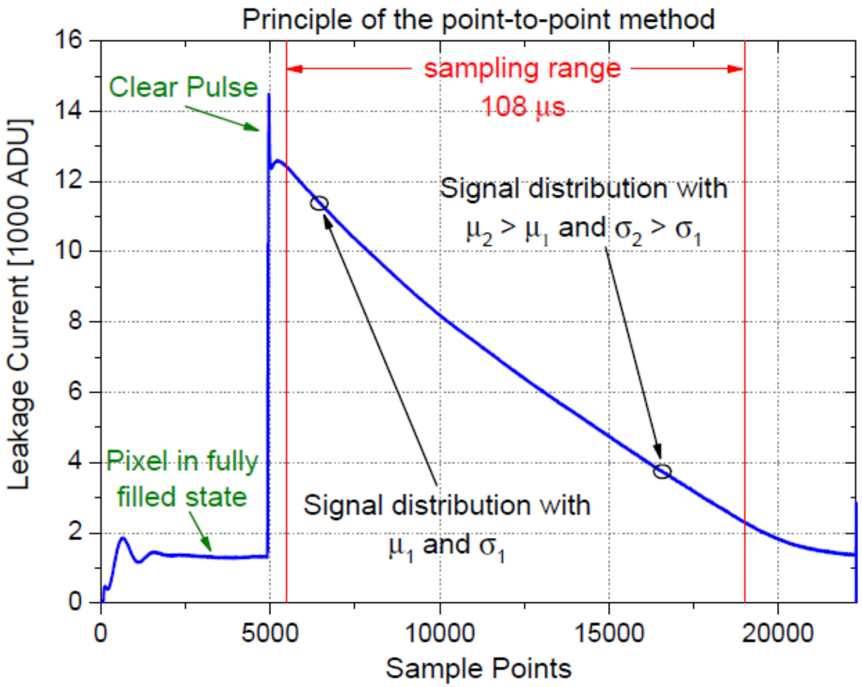
→ linearity mostly still present

→ decrease in voltage drop to change in effective dopant concentration

- behavior for large bulk currents was unfortunately dominated by the high resistivity bias resistor (R = 1 MΩ)

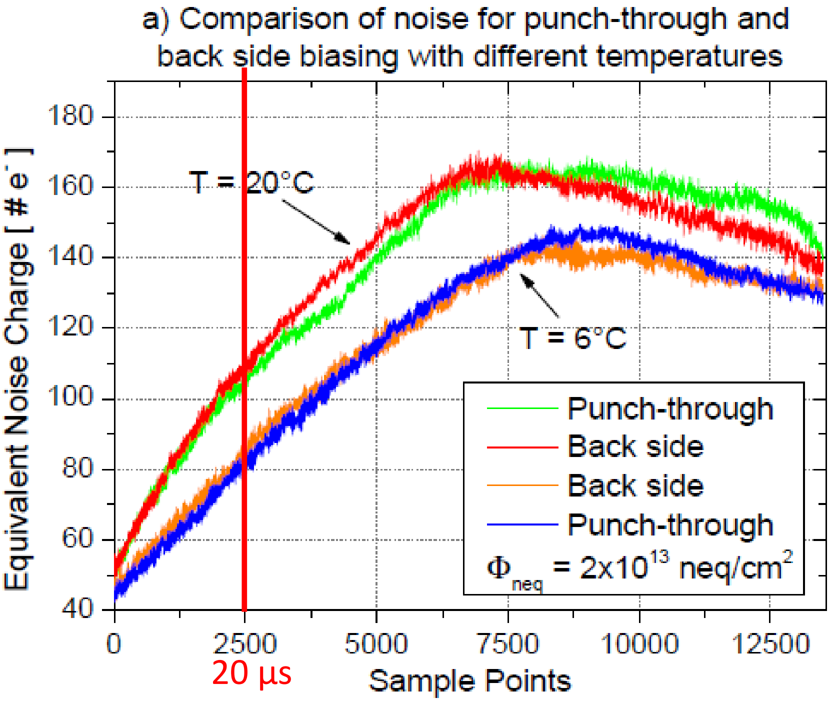
→ increased voltage drop at bias resistor leads to a decreasing effective punch-through voltage

Punch-through noise - methods



1 SP ≙ 8ns

Noise analysis of every time stamp with leakage current



Backup – Radioactivity

- neutron capture of electronics material (e.g. Cu or Au) will result in nuclear transformations

- daughter nucleus will exhibit radioactive decay processes, primarily $\beta^{\pm}$-radiation, which can be detected by the detector

➔ possible additional background source

For BELLE II: neutron fluence of approximately 10^{11} n/cm^{2}a will lead to a activity of less than 86 mBq

➔ **no issue for BELLE II**